



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20240229001.0
Datasheet for LMG342xR030 and LMG342xR050
Information Only**

Date: March 04, 2024
To: MOUSER PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the Change Management team.

Sincerely,

Change Management Team
SC Business Services

20240229001.0
Information Only Datasheet
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LMG3422R030RQZT	NULL
LMG3422R050RQZT	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20240229001.0	PCN Date:	March 04, 2024																																																				
Title:	Datasheet for LMG342xR030 and LMG342xR050																																																						
Customer Contact:	Change Management team	Dept:	Quality Services																																																				
Change Type:	Electrical Specification																																																						
PCN Details																																																							
Description of Change:																																																							
<p>Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.</p>																																																							
 TEXAS INSTRUMENTS		LMG3422R030, LMG3426R030 SNOSDA7E – SEPTEMBER 2020 – REVISED FEBRUARY 2024																																																					
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LMG3422R050, LMG3425R050

SNOSDA8C – OCTOBER 2020 – REVISED FEBRUARY 2024

Changes from Revision B (May 2022) to Revision C (February 2024)

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• Updated title and added sentence after figure in the <i>Repetitive SOA</i> section.....	15
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The datasheet number will be changing.

Device Family	Change From:	Change To:
LMG342xR030	SNOSDA7D	SNOSDA7E
LMG342xR050	SNOSDA8B	SNOSDA8C

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/LMG3422R030>

<http://www.ti.com/product/LMG3422R050>

Reason for Change:
To accurately reflect device characteristics.
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
Changes to product identification resulting from this PCN:
None.
Product Affected:
LMG3422R030RQZR LMG3422R030RQZT LMG3422R050RQZR LMG3422R050RQZT

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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